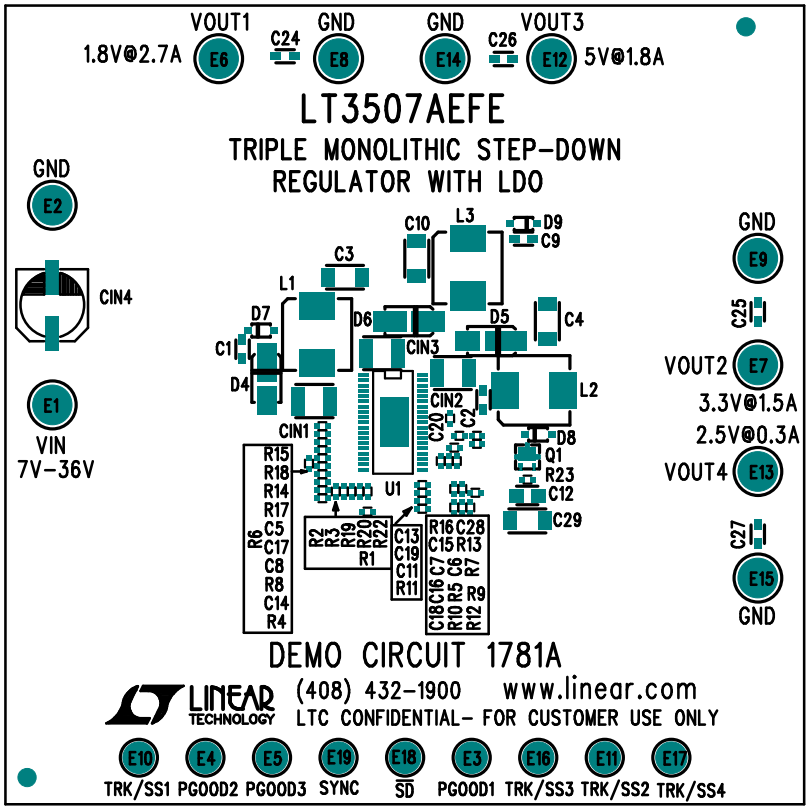
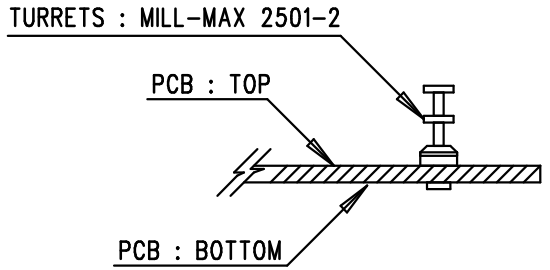
REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
	2	PRODUCTION	EDWIN L.	5-11-11



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.



APPROVALS	
PCB DES.	HZ
APP ENG.	EDWIN L.
SCALE = NONE	

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TITLE: TOP ASSEMBLY DRAWING

TRIPLE MONOLITHIC STEP-DOWN REGULATOR WITH LDO

SIZE	IC NO.	REV.
N/A	LT3507AEFE DEMO CIRCUIT 1781A	2

FILENAME: DC1781A-2.PCB | SHT 1 OF 2